

AMENDMENTS TO CLAIMS

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Original) A curable resin composition, comprising:
a curable resin intramolecularly having a silicon-containing functional group represented by general formula: $-\text{SiX}^1\text{X}^2\text{X}^3$ (wherein, X^1 , X^2 and X^3 respectively represent a hydrolytic group and may be the same as or different from each other); and
a Lewis acid or a complex of the Lewis acid, the Lewis acid being selected from the group consisting of metal halides and boron halides.
2. (Original) The curable resin composition according to Claim 1, wherein a part or all of the curable resin intramolecularly has at least one polar component selected from the group consisting of: urethane, thiourethane, urea, thiourea, substituted urea, substituted thiourea, amide and sulfide bonds; and hydroxyl, secondary amino and tertiary amino groups.
3. (Original) The curable resin composition according to Claim 1, wherein the curable resin comprises a resin having a number-average molecular weight of 500 to 50,000 and a viscosity (at 23°C) of 50 to 600,000 mPa·s that is liquid at room temperature.
4. (Original) The curable resin composition according to Claim 1, wherein each of the groupss X^1 , X^2 and X^3 of the silicon-containing functional group is a hydrolytic group selected from the group consisting of halogen, hydride, alkoxyl, acyloxy, ketoximate, amino, amido, aminooxy, mercapto and alkenyloxy groups.

5. (Original) The curable resin composition according to Claim 1, further comprising an aminosilane compound intramolecularly having a hydrolytic silyl or silanol group and an amino group.

6. (Original) The curable resin composition according to Claim 1, wherein the metal halide is selected from the group consisting of titanium chloride (IV), tin chloride (IV), zirconium chloride (IV), aluminum chloride (III), iron chloride, zinc chloride, copper chloride, antimony chloride, gallium chloride, indium chloride, titanium bromide, tin bromide, zirconium bromide, aluminum bromide, iron bromide, zinc bromide and copper bromide, and the boron halide is selected from the group consisting of boron trifluoride, boron trichloride, boron tribromide and boron triiodide.

7. (Currently Amended) The curable resin composition according to Claim 1, wherein the Lewis acid includes boron trifluoride, and the complex of the Lewis acid includes a complex selected from the group consisting of amine complex, alcohol complex and either complex.

8. (Original) The curable resin composition according to Claim 1, further comprising a mercaptosilane compound intramolecularly having a hydrolytic silyl or silanol group and a mercapto group.

9. (Original) The curable resin composition according to Claim 1, wherein the Lewis acid or the complex of the Lewis acid is contained in an amount of 0.001 to 10 parts by weight with respect 100 parts by weight of the curable resin.

10. (Original) The curable resin composition according to Claim 1, further comprising an organic tin compound in an amount of 0.01 to 10 parts by weight with respect to 100 parts by weight of the curable resin.

11. (Original) The curable resin composition according to Claim 10, wherein the organic tin compound includes a dioctyltin compound.

12. (Original) The curable resin composition according to Claim 1, for use as one selected from the group consisting of an adhesive, a sealant, a paint, a coating agent, a filler, a molding material and a coating material.

13. (Original) A curable resin composition, comprising:

a curable resin intramolecularly having: a silicon-containing functional group represented by general formula: $-\text{SiR}^1 \text{X}^1 \text{X}^2$ (wherein X^1 and X^2 respectively represent a hydrolytic group and may be the same as or different from each other, and R^1 represents a substituted or unsubstituted organic group having 1 to 20 carbons); and at least one polar component selected from the group consisting of urethane, thiourethane, urea, thiourea, substituted urea, substituted thiourea, amide, and sulfide bonds, and hydroxyl, secondary amino and tertiary amino groups; and

a Lewis acid or a complex of the Lewis acid, the Lewis acid being selected from the group consisting of metal halides and boron halides.

14. (Original) The curable resin composition according to Claim 13, wherein each of the groups X^1 and X^2 of the silicon-containing functional group is a hydrolytic group selected from the group consisting of halogen, hydride, alkoxyl, acyloxy, ketoximate, amino, amide, aminooxy, mercapto and alkenyloxy groups,

the metal halide is selected from the group consisting of titanium chloride (IV), tin chloride (IV), zirconium chloride (IV), aluminum chloride (III), iron chloride, zinc chloride, copper chloride, antimony chloride, gallium chloride, indium chloride, titanium bromide, tin bromide, zirconium bromide, aluminum bromide, iron bromide, zinc bromide and copper bromide,

and the boron halide is selected from the group consisting of boron trifluoride, boron trichloride, boron tribromide and boron triiodide.

15. (Original) The curable resin composition according to Claim 13, further comprising an aminosilane compound intramolecularly having a hydrolytic silyl or silanol group and an amino group.

16. (Currently Amended) The curable resin composition according to Claim 13, wherein the Lewis acid includes boron trifluoride, and the complex of the Lewis acid includes a complex selected from the group consisting of amine complex, alcohol complex and ether complex.

17. (Original) The curable resin composition according to Claim 13, further comprising a mercaptosilane compound intramolecularly having a hydrolytic silyl or silanol group and a mercapto group.

18. (Original) A cold-setting adhesive, comprising:
a curable resin having a silicon-containing functional group represented by general formula: $-\text{SiX}^1\text{X}^2\text{X}^3$ (wherein, X^1 , X^2 and X^3 respectively represent a hydrolytic group and may be the same as or different from each other); and
a Lewis acid or a complex of the Lewis acid, the Lewis acid being selected from the group consisting of metal halides and boron halides.

19. (Original) The cold-setting adhesive according to Claim 18, comprising two agents that are mixed during use, wherein the curable resin and the Lewis acid or the complex of the Lewis acid are contained separately in one of the two agents.